

cont'd

then cures to a substantially solid condition, the protective barrier preventing the encapsulation material from contacting the terminals on the top layer.

Claim 45, line 2, change "encapsulation barrier" to read -- encapsulant barrier --.

Claim 46, line 2, change "encapsulation barrier" to read -- encapsulant barrier --.

Claim 47, line 2, change "encapsulation barrier" to read -- encapsulant barrier --.

Cancel claims 48-52 inclusive.

In the Specification:

Page 9, line 20 change "29" to -- 31 --.

In the Drawings:

Amend the drawings in accordance with the enclosed red-marked prints.

REMARKS

revised

The present amendment is responsive to the final Official Action mailed June 24, 1996. A petition for a three month extension of the shortened statutory time period for response to said Official Action is transmitted herewith. Also, although it is believed that the present amendment will place the case in condition for allowance, a notice of appeal is transmitted herewith so that the present response, with said notice of appeal, conforms to the requirements of 37 CFR 1.113. The present amendment is also intended to effectuate the discussion at the personal interview of October 2, 1996 between undersigned counsel and Examiner Richard D. Lovering. The Examiner's courtesy and cooperation in granting and conducting said interview are greatly appreciated.

At the interview, undersigned counsel noted that the step of "providing a protective barrier" in claim 1 referred to the step of providing an element in contact with the "top layer" of the chip assembly itself. For example, in applicants' Fig. 1, terminals 26 are disposed on a polymeric top layer 16 and a further layer or sheetlike mask 30 is applied over the top layer so that the mass engages the top layer 16. In this embodiment, the protective

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